



Smart Resilient Manufacturing

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closed (20 June 2022)

Message from the Guest Editors

In recent decades, the global manufacturing industries have been reshaped by the rapid development of advanced technologies, such as the Internet of Things, Artificial Intelligence (AI), machine learning, cloud/edge computing, smart sensing, advanced robotics, blockchain/distributed ledger technology, etc. These have fostered the concept of smart manufacturing as the next-generation manufacturing paradigm, which is the core of Industry 4.0.

This Special Issue invites authors to submit their high-quality research articles that cover different topics of smart manufacturing including, but not limited to, data-driven smart manufacturing, Industrial Internet of Things (IIoT), data sharing for manufacturing, advanced cyber-physical production systems (CPPS), innovative models and reference architectures, industrial semantics and ontologies, process/quality optimization, applications of AI/machine learning in manufacturing, cyber security and blockchains in manufacturing, digital and cognitive twins for manufacturing, etc. This call also welcomes contributions that explore methodologies and practices of resilient manufacturing aiming to address the COVID-19 pandemic's impact.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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